

Digital Back-End (DBE) development at SAO for the ngEHT

G.Gancio in rep of the ngEHT DBE Design Team



Digital BackEnd definition

IAR roadmap on digital backends (DBE)

EHT vs ngEHT DBE requirements

System block diagram of DBE

DBE Firmware Block

16 Gsps ADC Characterization

Integrated ADC/FPGA board

Current status

ADC alignment (waveforms)

Resources used

What's next ??

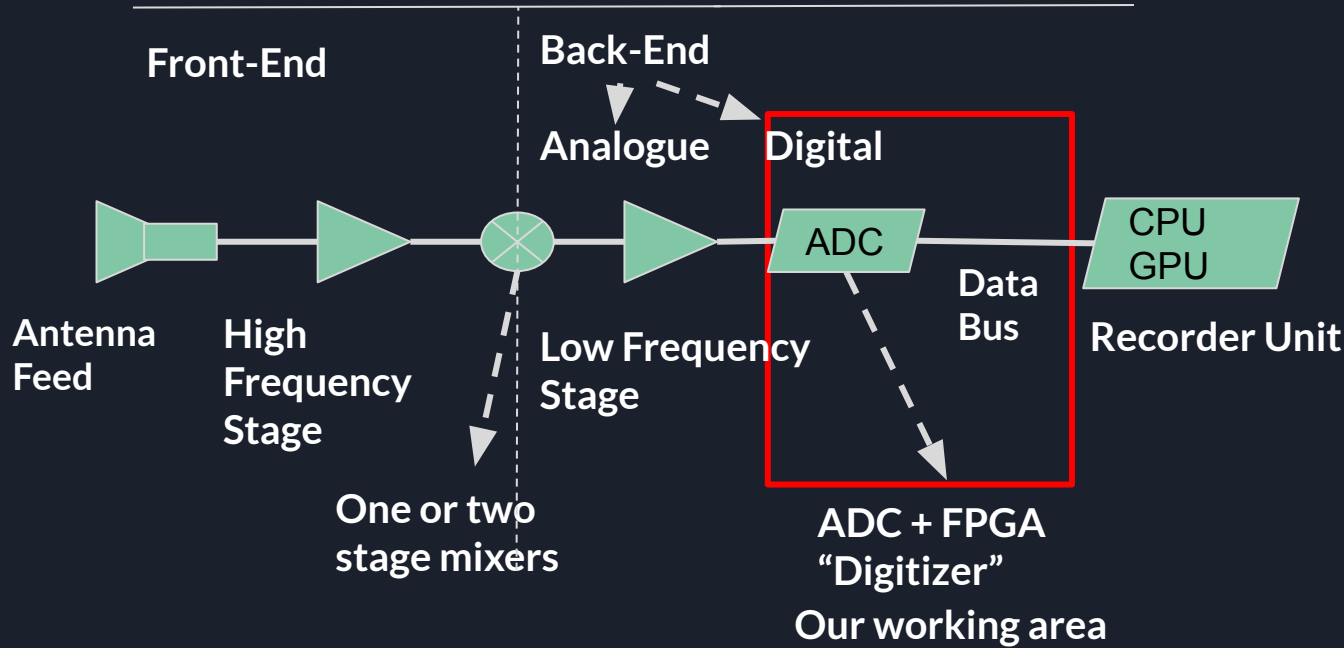
CMAC Interface

1 Gb interface

Storage on a 2nd VCU128

Channelization

Digital Backend (DBE) Definition and main aspects



Main aspects for this talk:

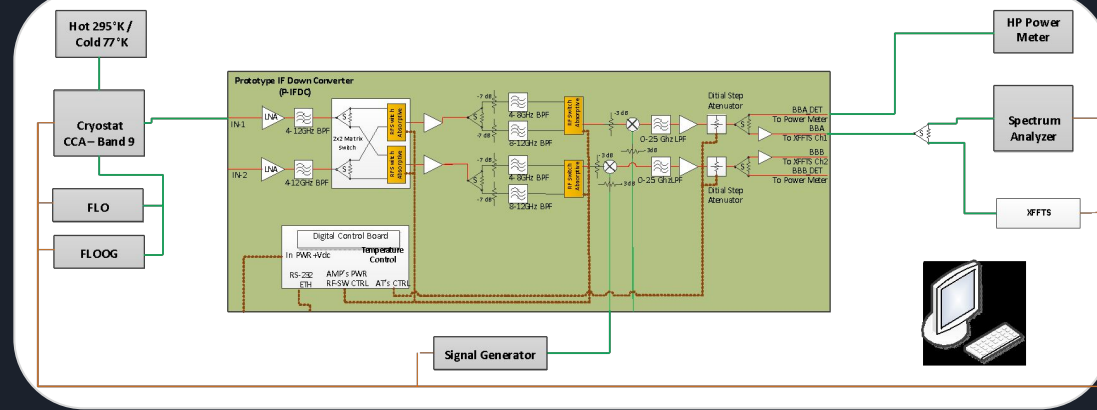
- Acquisition Bandwidth
- Processing capability
- Output data rate

IAR DBEs Roadmap Highlights

2017 RPG XFFTS LLAMA Spectrometer

- 16G Hz BW Total
- Divided in 8ch 2.5GHz BW
- 8+1 1Gbps Ethernet connection

Tested at NOVA Netherlands
with Band-5 & Band-9 Submm Rxs



Prototype Downconverter Block Design:

J.J.Larrarte & G.Gancio - IAR

J.P. Garcia - LLAMA

Engineer Software:

D. Zanella, - USP

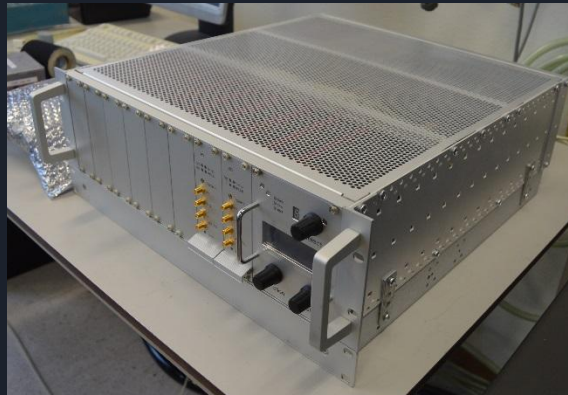
F. Hauscarriaga & G. Gancio - IAR

System Integration and Test at Nova: NOVA Team

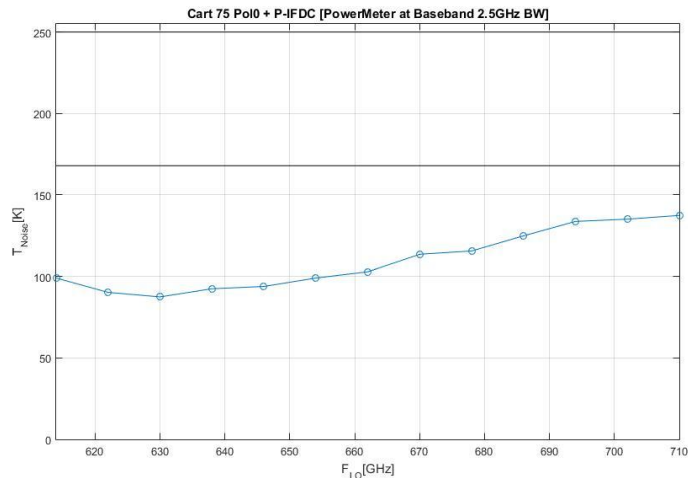
G.Gancio - IAR

M.Luqueze - USP

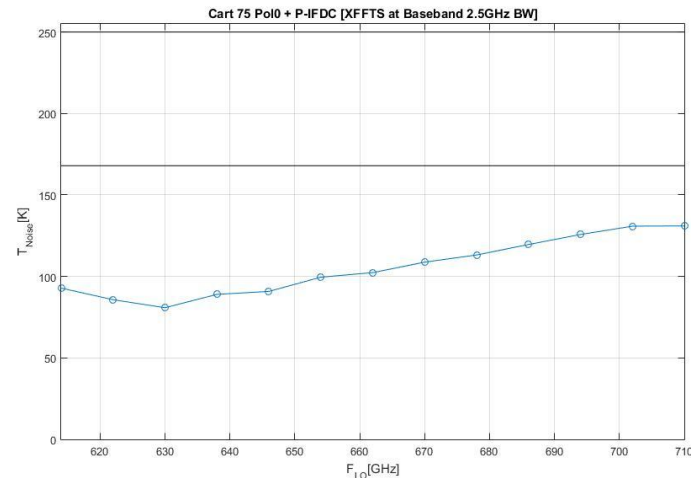
S. Verri - USP



IAR DBEs Roadmap Highlights



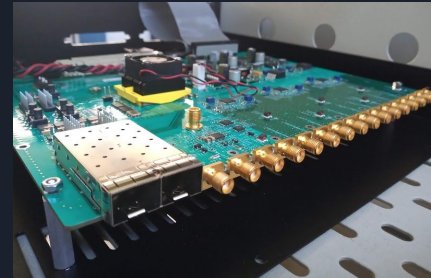
Power Meter Readout



XFITS Readout

IAR DBEs Roadmap Highlights

- 2018 Ettus Boards one B210, four B205 as digitizers. will all the process on CPUs. PuMa BackEnd Pulsar research.
 - 56 MHz BW Each, Data over USB 3.0 5 Gb/s [224 MHz Total BW]
- 2020 ROACH with CASPER Toolflow (IRyA - Mexico). Single Dish Pulsars, Continuum
 - x4 100 MHz BW, Data over x4 10 Gb/s [400 MHz Total BW]
- 2022 x1 SNAP Board with CASPER Toolflow, for the Multipurpose Interferometer ARRAY
 - Total of 6 Ch 250 MHz Bw To distribute, Data over x2 10 Gb/s [1.5 GHz Total BW]
- 2022 x2 RFSoc with CASPER Toolflow, for Spectral Line, Continuum experiments
 - 2 ch with 2 GHz Bandwidth each, Data over x 1Gb/s [4 GHz BW Total BW]



ngEHT DBE 2022 Team



Eng. Test



PhD. Weintroub



Eng. Haworth



Eng. Srinivasan



PhD. Pola



Mr. Gancio



Eng. Gendelman



Eng. Fliger



Eng. Habiague



Eng. Canadea



Eng. Cabral



Ms. Mamani



Mr. Fernandez



Lic. Araujo



Eng. Viglianco

R2DBE EHT DBE:

- Use of ROACH-2 boards with CASPER Toolflow
- RF in 2x 2048 MHz BW [4096 MHz Total BW]
- Sampling Rate 4096 MSPS
- Total Data Rate 16 Gbps
- Xilinx FPGA Virtex-6
- Output format VDIF

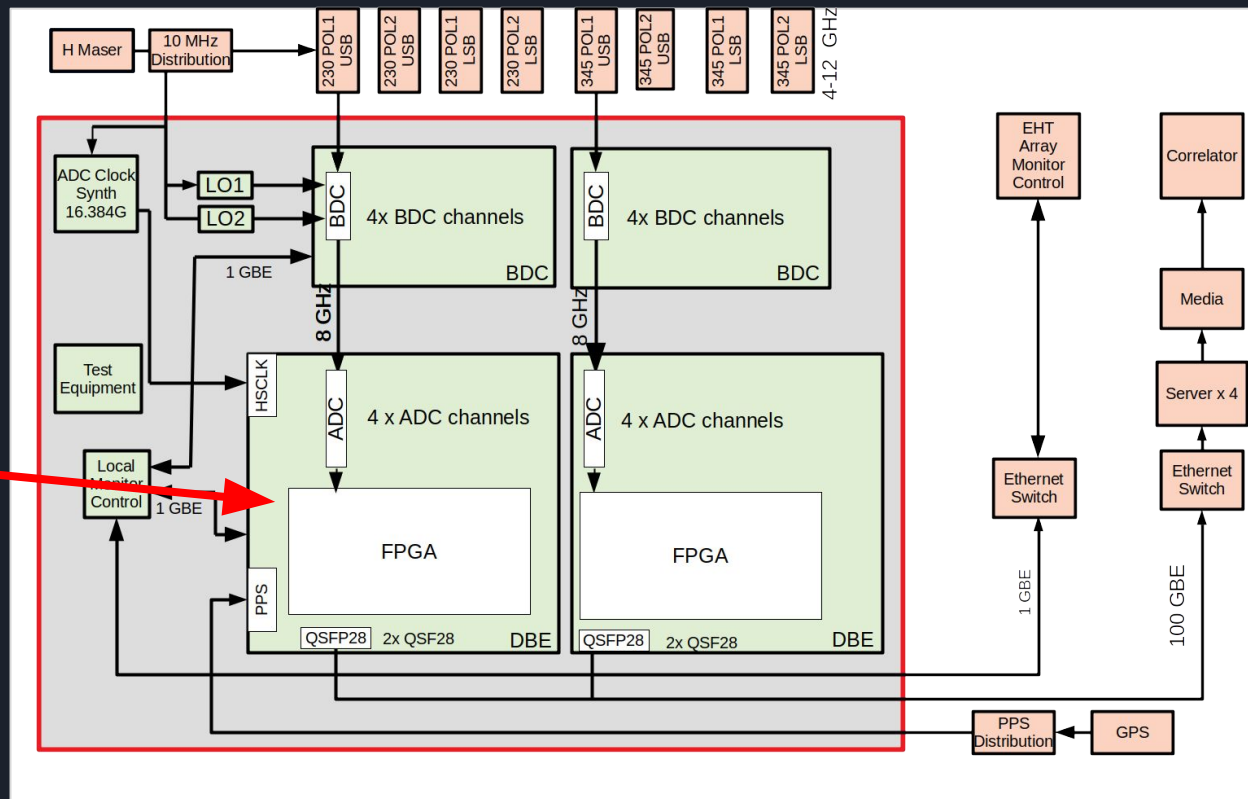
ngEHT DBE:

- Custom Board
- RF in 2x8 GHz BW [32 GHz Total BW]
- Sampling Rate 16.384 GSPS
- Total Data Rate 64 Gbps
- Xilinx FPGA Ultrascale Family
- Output format VDIF

R2DBE: A Wideband Digital Backend for the Event Horizon Telescope
<http://dx.doi.org/10.1086/684513>

ngEHT BackEnd Block Diagram

ngEHT DBE Board



DBE Prototype ADC board + VCUs board Setups

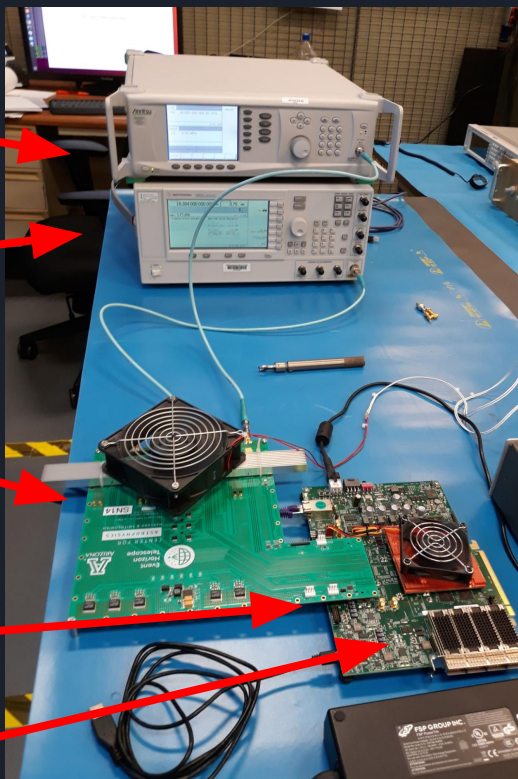
Tone source

Clock
16.384 GHz

4 channel
ADC board

VCU128

100 Gb



SAO Setup

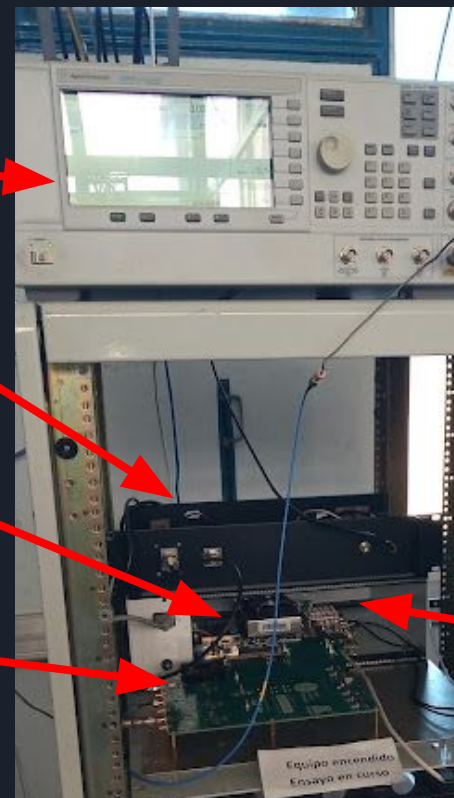
Clock
16.384 GHz

Tone source

VCU118

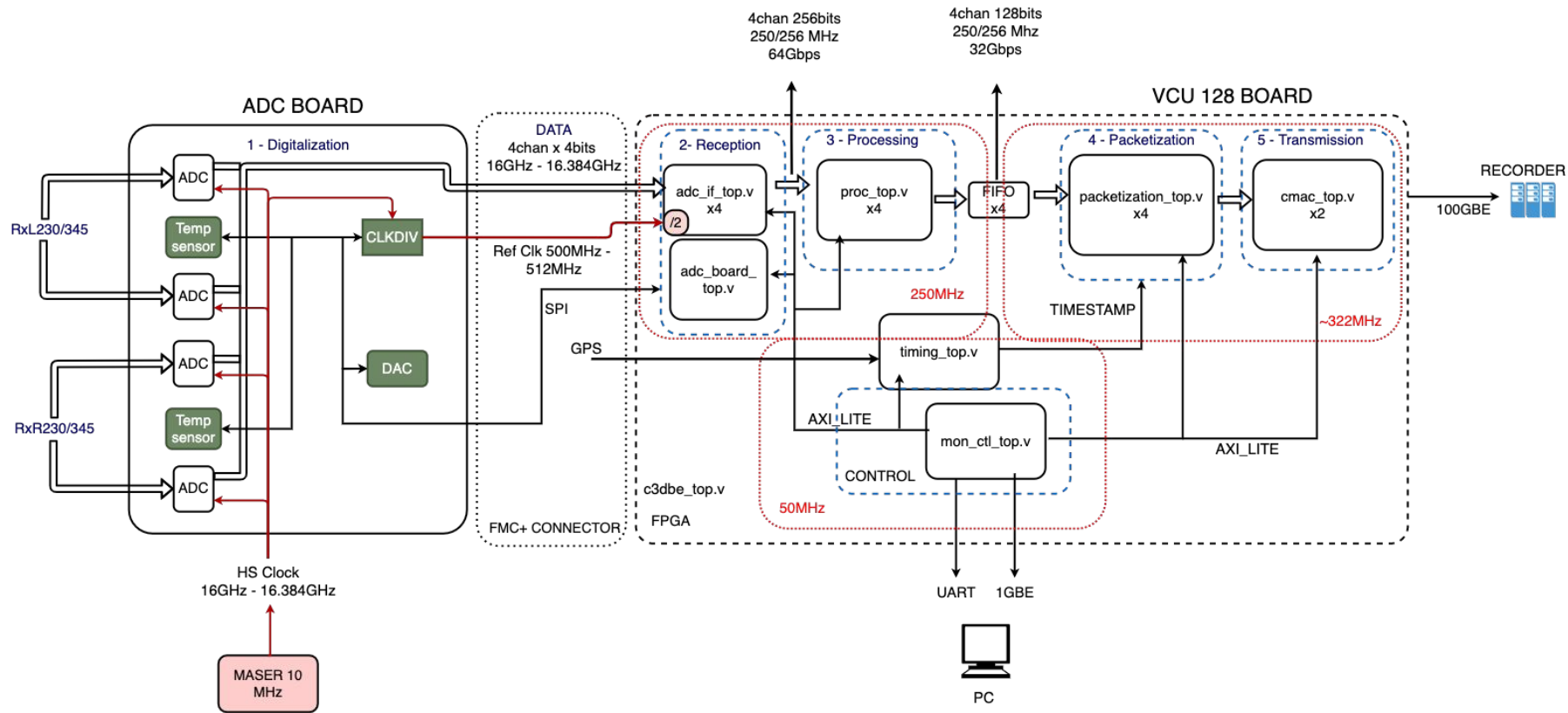
1 channel
ADC board

100 Gb



IAR Setup

DBE Firmware



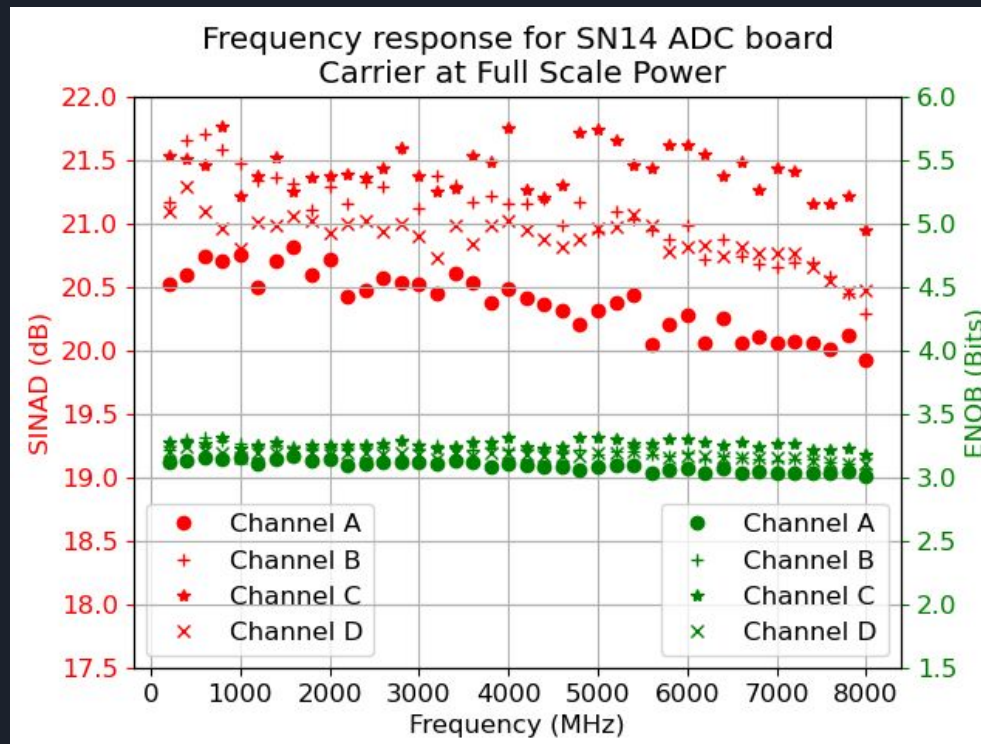
ADC Characterization

SINAD:

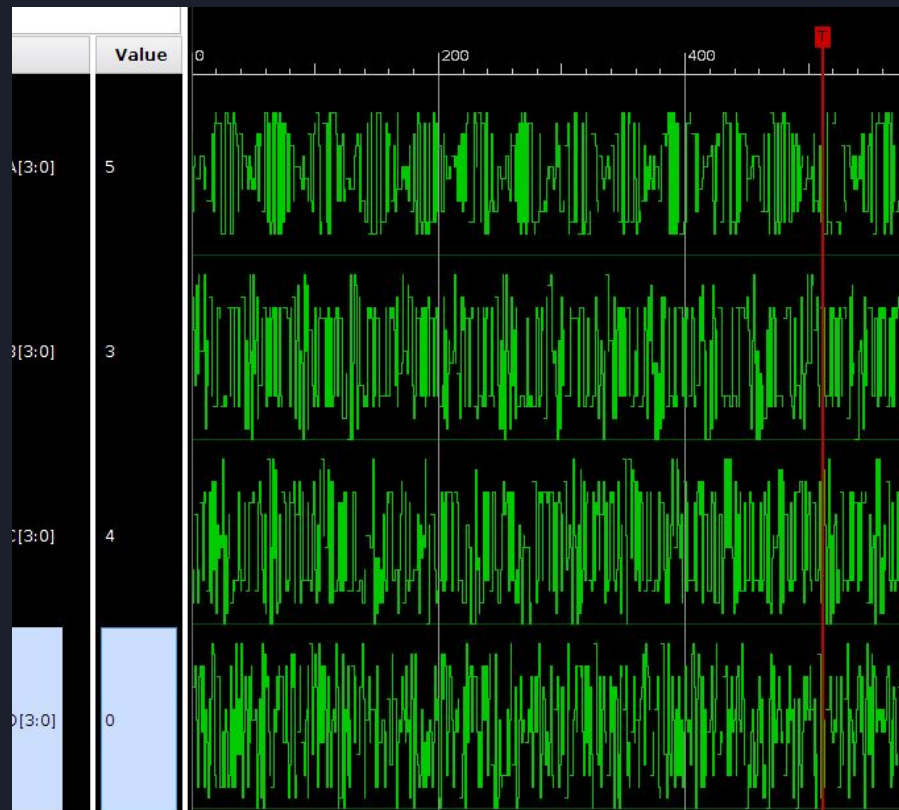
- Signal to Noise And Distortion

ENOB:

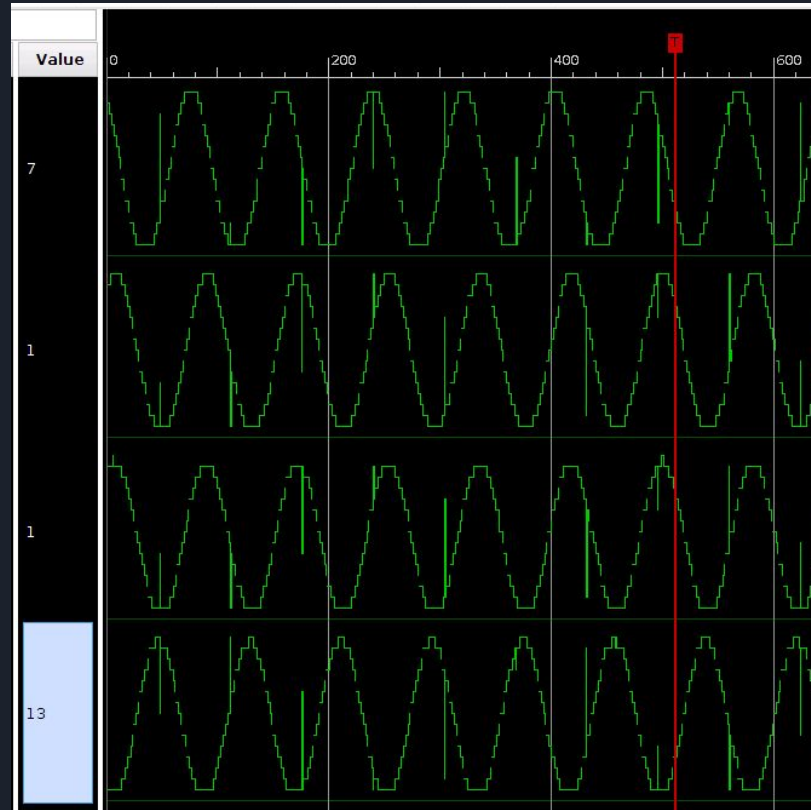
- Effective Number of Bits



ADC Alignment

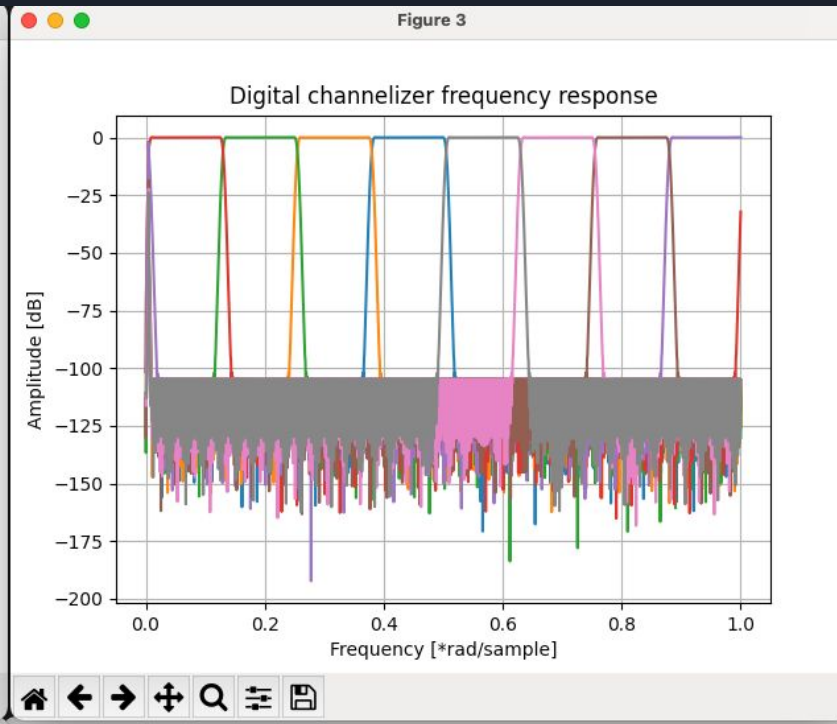
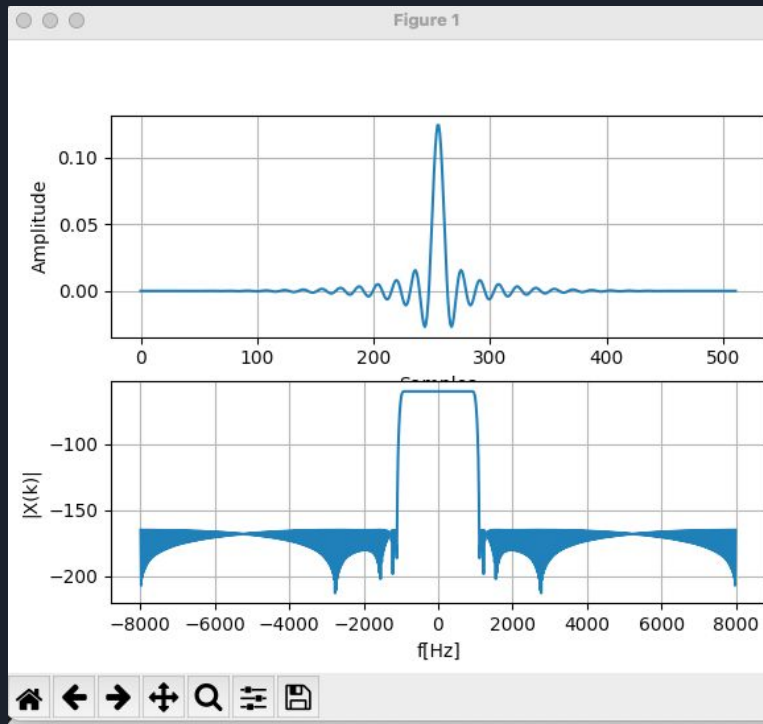


Results without alignment



Results with alignment

Channelization



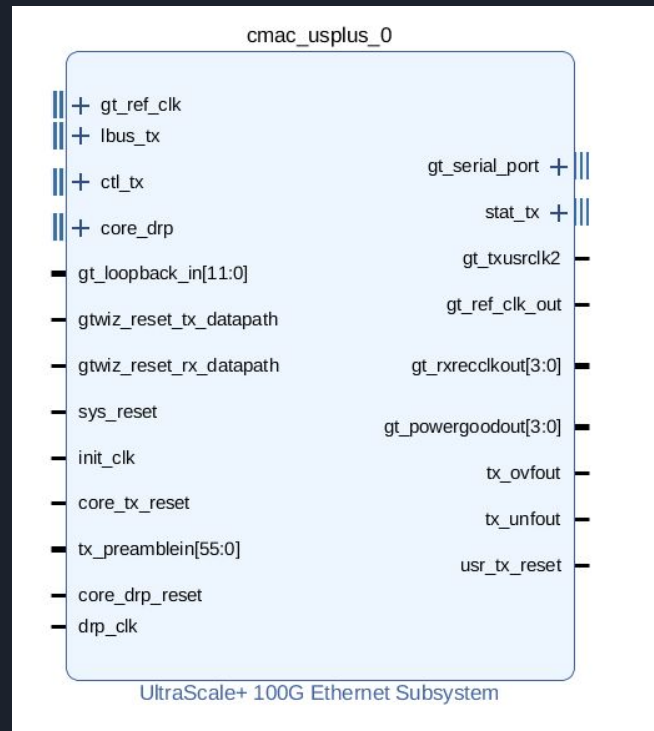
100 Gbps CMAC Interface

- What has been done?

At this point there hasn't been any packet loss, which means that every packet sent to the MAC is being accepted and transferred to the PHY

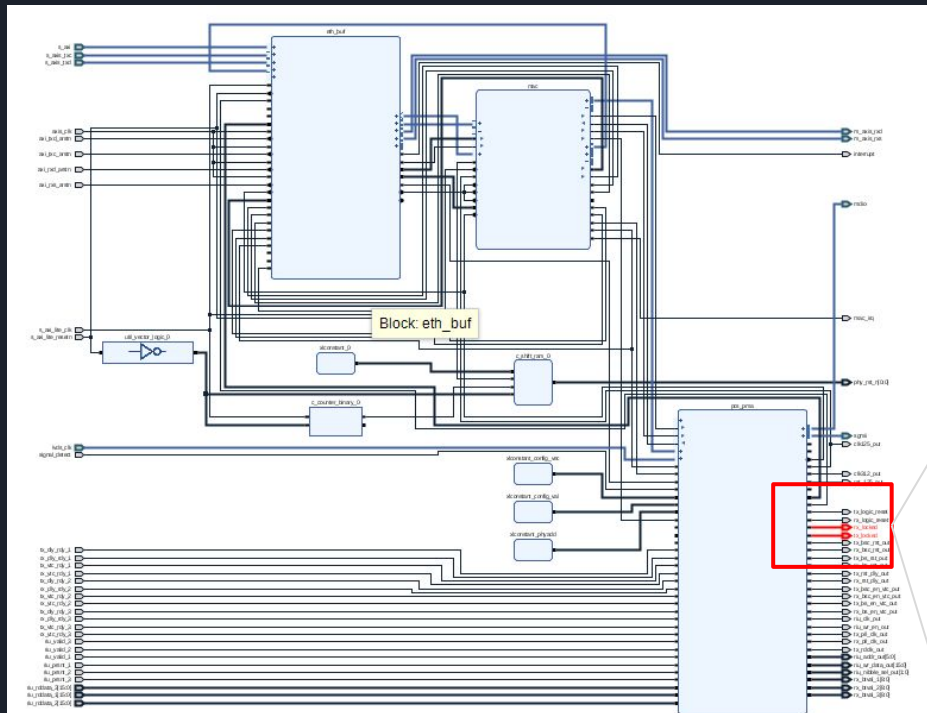
- What is still to cover?

The connection between the switch and the FPGA is off because we need a licence by Xilinx to bring up the copper based mediums link

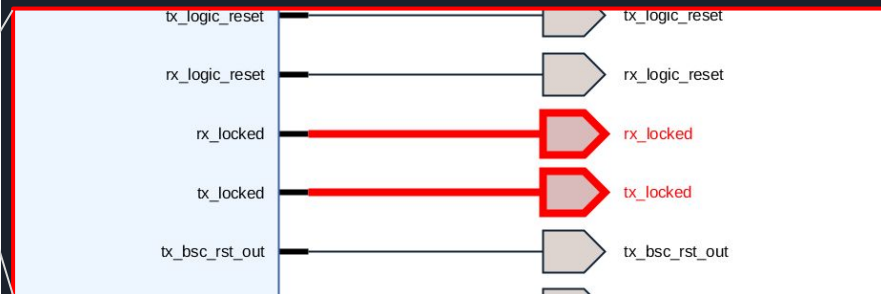


© Xilinx Inc. Vivado IDE. UltraScale+ 100G Ethernet Subsystem

1Gb Ethernet Interface

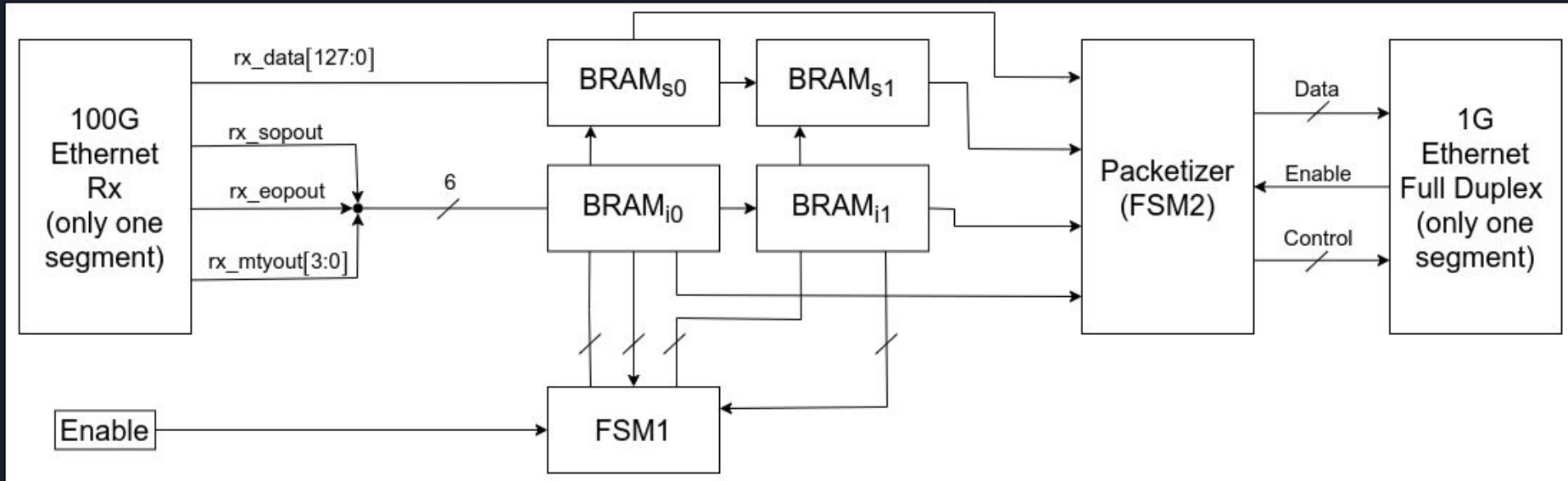


The 1 Gb Ethernet is currently being debugged because some intermittency was found in the signal provided by the following pins. We've come to the conclusion that this may be the cause of the issue related to the bad connection through this interface.



© Xilinx Inc. Vivado IDE. AXI 1G/2.5G Ethernet Subsystem

Storage (Separate VCU128)



Integrated PCB vs Available Boards

Why not use the 4 channel ADC board + VCU128 ??

- FMC+ connector not a reliable high speed connector
- Having intermittent connectivity issues with the 1 Gb
- Not sure about performance when board resources start to get used up (DSP slices)
- Several resources not being used that Consumes lots of Power (PCIe, Transceivers, Clocks)
- Difficult to comply with thermal dissipation

A new PCB will:

- Integrate in a single board the ADCs and FPGA with a better signal integrity
- Take into consideration thermal issues for a good heat dissipation
- Less power consumption by removing all unnecessary electronics (PCIe, Transceivers, etc)
- Better housekeeping design for telemetry control.

Design Team for the PCB has started the design process

- The DBE prototype should be delivered End 2022 / Beginning 2023
- We are expecting to measure the throughput in the near future.
- We are hoping to have a custom board for the FPGA/ADC for the fringe test.
- We are hoping to have a scaled down channelized version of the firmware also for the fringe test.
- A system integration end to end test must be performed with the Block Down Converter (BDC) and DBE before the OVRO/LMT fringe test. (End of 2023)